The listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1.-12. (Canceled)

13. (Previously Presented) The device of claim 40 wherein said active matrix circuit comprises an amorphous silicon transistor, and said driver circuit comprises a crystalline silicon transistor.

14. (Previously Presented) The device of claim 40 wherein said active matrix circuit comprises a MIM diode.

15. (Previously Presented) The device of claim 40 wherein said resin material comprises a material selected from the group consisting of an epoxy resin and an ultraviolet hardening resin.

16.-20. (Canceled)

21. (Previously Presented) The device of claim 40 wherein said sealing agent contains spacers.

22.-23. (Canceled)

24. (Previously Presented) The device of claim 42 wherein said sealing agent contains spacers.

25. (Previously Presented) An active matrix type display device comprising:

a first substrate;

an active matrix circuit having a plurality of pixels arranged in a matrix form over said first substrate;

at least one driver circuit for driving said active matrix circuit over said first substrate, there being at least one side of said first substrate at which no driver circuit is disposed, and each of said active matrix circuit and said driver circuit comprising thin film transistors provided over said first substrate;

a second substrate opposed to said first substrate;

a liquid crystal provided between said first substrate and said second substrate;

a resin material provided between said first and second substrates, said resin material covering said driver circuit;

a sealing agent provided between said first substrate and said second substrate for sealing said liquid crystal therebetween, said sealing agent enclosing said active matrix circuit and said driver circuit;

an inlet for injecting said liquid crystal between said first substrate and said second substrate,

wherein said inlet is provided to said sealing agent and on a side edge of said first substrate and said second substrate corresponding to said one side of said first substrate.

26. (Previously Presented) The device of claim 25 wherein the thin film transistors of each of said active matrix circuit and said driver circuit are formed over said first substrate through a common process.

27. (Previously Presented) The device of claim 25 wherein said sealing agent overlaps at least a part of said driver circuit.

28. (Previously Presented) The device of claim 25 wherein a same material as said sealing agent is provided over at least said driver circuit.

29. (Previously Presented) The device of claim 25 wherein said sealing agent comprises an ultraviolet-curable resin.

30.-34. (Canceled)

35. (Previously Presented) An active matrix type display device comprising:

a first substrate;

an active matrix circuit having a plurality of pixels arranged in a matrix form over said first substrate;

at least one driver circuit for driving said active matrix circuit over said first substrate, there being at least one side of said first substrate at which no driver circuit is disposed, and each of said active matrix circuit and said driver circuit comprising thin film transistors provided over said first substrate;

a second substrate opposed to said first substrate wherein an electrical element is provided over the second substrate at least at a region opposed to the driver circuit;

a liquid crystal provided between said first substrate and said second substrate;

a resin material provided between said first and second substrates, said resin material covering said driver circuit;

a sealing agent provided between said first substrate and said second substrate for sealing said liquid crystal therebetween, said sealing agent enclosing said active matrix circuit and said driver circuit; and

an inlet for injecting said liquid crystal between said first substrate and said second substrate,

wherein said inlet is provided to said sealing agent and on a side edge of said first substrate and said second substrate corresponding to said one side of said first substrate,

wherein said second substrate has at least one side edge which is substantially aligned with a side edge of said first substrate and an outer edge of said sealing agent, and

wherein an electrical connection is established between said driver circuit and said electrical element by at least one silver paste or at least one electrically conductive spacer.

36. (Previously Presented) The device of claim 35 wherein said thin film transistor of each of said active matrix elements and said driver circuit is formed through a common process.

37. (Previously Presented) The device of claim 35 wherein said sealing agent overlaps at least a part of said driver circuit.

38. (Previously Presented) The device of claim 35 wherein a same material as said sealing agent is provided over at least said driver circuit.

39. (Previously Presented) The device of claim 35 wherein said sealing agent comprises an ultraviolet-curable resin.

40. (Previously Presented) An active matrix type display device comprising:

a first substrate;

an active matrix circuit having a plurality of pixels arranged in a matrix form over said first substrate;

at least one driver circuit for driving said active matrix circuit over said first substrate, there being at least one side of said first substrate at which no driver circuit is disposed, and each of said active matrix circuit and said driver circuit comprising thin film transistors provided over said first substrate;

a second substrate opposed to said first substrate;

a liquid crystal provided between said first substrate and said second substrate;

a resin material provided between said first and second substrates, said resin material covering said driver circuit;

a sealing agent provided between said first substrate and said second substrate and enclosing said active matrix circuit and said driver circuit; and

an inlet for injecting said liquid crystal between said first substrate and said second substrate,

wherein said inlet is provided to said sealing agent and on a side edge of said first substrate and said second substrate corresponding to said one side of said first substrate.

41. (Canceled)

42. (Previously Presented) An active matrix type display device comprising:

a first substrate;

an active matrix circuit having a plurality of pixels arranged in a matrix form over said first substrate;

at least one driver circuit for driving said active matrix circuit over said first substrate, there being at least one side of said first substrate at which no driver circuit is disposed, and each of said active matrix circuit and said driver circuit comprising thin film transistors provided over said first substrate;

a second substrate opposed to said first substrate wherein an electrical element is provided over the second substrate at least at a region opposed to the driver circuit;

a liquid crystal provided between said first substrate and said second substrate;

a resin material provided between said first and second substrates, said resin material covering said driver circuit;

a sealing agent provided between said first substrate and said second substrate and enclosing said active matrix circuit and said driver circuit;

a first inlet provided for introducing said liquid crystal between said first substrate and said second substrate; and

a second inlet provided for introducing said resin material between said first substrate and said second substrate,

wherein said first inlet is provided to said sealing agent and on a side edge of said first substrate and said second substrate corresponding to said one side of said first substrate, and

wherein an electrical connection is established between said driver circuit and said electrical element by at least one silver paste or at least one electrically conductive spacer.

43.-44. (Canceled)

45. (Previously Presented) The device of claim 25 wherein said second substrate has at least one side edge which is substantially aligned with a side edge of said first substrate.

46.-55. (Canceled)

56. (Previously Presented) An active matrix type display device comprising:

a first substrate;

an active matrix circuit having a plurality of pixels arranged in a matrix form over said first substrate;

at least one first driver circuit for driving said active matrix circuit over said first substrate, there being at least one side of said first substrate at which no first driver circuit is disposed, and each of said active matrix circuit and said first driver circuit comprising thin film transistors provided over said first substrate;

a second substrate opposed to said first substrate wherein a second driver circuit is provided over the second substrate at a region opposed to the first driver circuit;

a liquid crystal provided between said first substrate and said second substrate;

a resin material provided between said first and second substrates, said resin material covering said driver circuit;

a sealing agent provided between said first substrate and said second substrate for sealing said liquid crystal therebetween, said sealing agent enclosing said active matrix circuit and said first driver circuit;

an inlet for injecting said liquid crystal between said first substrate and said second substrate,

wherein said inlet is provided to said sealing agent and on a side edge of said first substrate and said second substrate corresponding to said one side of said first substrate.

57. (Previously Presented) The device of claim 56 wherein the thin film transistors of each of said active matrix circuit and said first driver circuit are formed over said first substrate through a common process.

58. (Previously Presented) The device of claim 56 wherein said sealing agent overlaps at least a part of said first driver circuit.

59. (Previously Presented) The device of claim 56 wherein a same material as said sealing agent is provided over at least said first driver circuit.

60. (Previously Presented) The device of claim 56 wherein said sealing agent comprises an ultraviolet-curable resin.

61. (Previously Presented) An active matrix type display device comprising:

a first substrate;

an active matrix circuit having a plurality of pixels arranged in a matrix form over said first substrate;

at least one driver circuit for driving said active matrix circuit over said first substrate, there being at least one side of said first substrate at which no driver circuit is disposed, and each of said active matrix circuit and said driver circuit comprising thin film transistors provided over said first substrate;

a second substrate opposed to said first substrate;

a liquid crystal provided between said first substrate and said second substrate;

a resin material provided between said first and second substrates, said resin material covering said driver circuit;

a sealing agent provided between said first substrate and said second substrate for sealing said liquid crystal therebetween, said sealing agent enclosing said driver circuit;

an inlet for injecting said liquid crystal between said first substrate and said second substrate,

wherein said inlet is provided to said sealing agent and on a side edge of said first substrate and said second substrate corresponding to said one side of said first substrate.

62. (Previously Presented) The device of claim 61 wherein the thin film transistors of each of said active matrix circuit and said driver circuit are formed over said first substrate through a common process.

63. (Previously Presented) The device of claim 61 wherein said sealing agent contains spacers.

64. (Previously Presented) The device of claim 61 wherein said sealing agent comprises an ultraviolet-curable resin.

65. (Previously Presented) The device of claim 61 wherein said second substrate has at least one side edge which is substantially aligned with a side edge of said first substrate.

66. (Previously Presented) An active matrix type display device comprising:

a first substrate;

an active matrix circuit having a plurality of pixels arranged in a matrix form over said first substrate;

at least one driver circuit for driving said active matrix circuit over said first substrate, there being at least one side of said first substrate at which no driver circuit is disposed, and each of said active matrix circuit and said driver circuit comprising thin film transistors provided over said first substrate;

a second substrate opposed to said first substrate;

a liquid crystal provided between said first substrate and said second substrate;

a resin material provided between said first and second substrates, said resin material covering said driver circuit;

a sealing agent provided between said first substrate and said second substrate and enclosing said driver circuit; and

an inlet for injecting said liquid crystal between said first substrate and said second substrate,

wherein said inlet is provided to said sealing agent and on a side edge of said first substrate and said second substrate corresponding to said one side of said first substrate.

67. (Previously Presented) The device of claim 66 wherein the thin film transistors of each of said active matrix circuit and said driver circuit are formed over said first substrate through a common process.

68. (Previously Presented) The device of claim 66 wherein said sealing agent contains spacers.

69. (Previously Presented) The device of claim 66 wherein said sealing agent comprises an ultraviolet-curable resin.

70. (Previously Presented) The device of claim 66 wherein said second substrate has at least one side edge which is substantially aligned with a side edge of said first substrate.